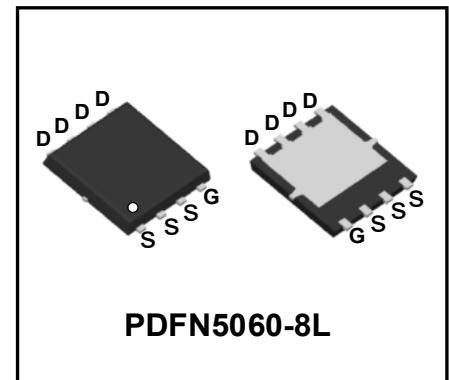


## 40V N-Channel Enhancement Mode Power MOSFET

### Description

WMB100N04TS uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.



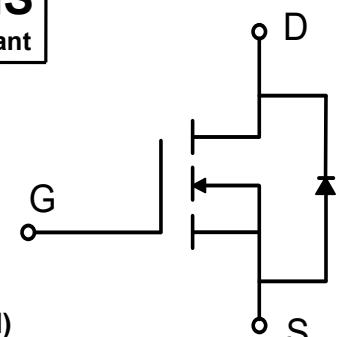
### Features

- $V_{DS} = 40V$ ,  $I_D = 125A$   
 $R_{DS(on)} < 3.6m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 4.6m\Omega$  @  $V_{GS} = 4.5V$
- High Density Cell Design
- Low  $R_{DS(on)}$
- 100% EAS Guaranteed



### Applications

- Power Management Switches
- DC/DC Converter



### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

| Parameter  | Symbol         | Value      | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage                             | $V_{DS}$       | 40         | V    |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$   | V    |
| Continuous Drain Current<br>$T_c=25^\circ C$     | $I_D$          | 125        | A    |
|  |                | 79         |      |
| Pulsed Drain Current <sup>1</sup>                | $I_{DM}$       | 500        | A    |
| Single Pulse Avalanche Energy <sup>2</sup>       | $E_{AS}$       | 135.2      | mJ   |
| Total Power Dissipation<br>$T_c=25^\circ C$      | $P_D$          | 96         | W    |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 to 150 | °C   |

### Thermal Characteristics

| Parameter  | Symbol   | Value | Unit |
|--|----------|-------|------|
| Thermal Resistance from Junction-to-Ambient <sup>3</sup> | $R_{JA}$ | 49    | °C/W |
| Thermal Resistance from Junction-to-Case                 | $R_{JC}$ | 1.3   | °C/W |

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

| Parameter  | Symbol                      | Test Conditions   | Min. | Typ. | Max.      | Unit             |
|--|-----------------------------|---|------|------|-----------|------------------|
| <b>Static Characteristics</b>  |                             |   |      |      |           |                  |
| Drain-Source Breakdown Voltage   | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$   | 40   | -    | -         | V                |
| Gate-body Leakage current  | $I_{\text{GSS}}$            | $V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$                               | -    | -    | $\pm 100$ | nA               |
| Zero Gate Voltage Drain Current<br>$T_J=25^\circ\text{C}$<br>$T_J=100^\circ\text{C}$ | $I_{\text{DSS}}$            | $V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$                                   | -    | -    | 1         | $\mu\text{A}$    |
|  |                             |   | -    | -    | 100       |                  |
| Gate-Threshold Voltage   | $V_{\text{GS}(\text{th})}$  | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$                                     | 1    | 1.6  | 2.5       | V                |
| Drain-Source On-Resistance <sup>4</sup>  | $R_{\text{DS}(\text{on})}$  | $V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$  | -    | 2.6  | 3.6       | $\text{m}\Omega$ |
|  |                             | $V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$   | -    | 3.4  | 4.6       |                  |
| Forward Transconductance <sup>4</sup>  | $g_{\text{fs}}$             | $V_{\text{DS}} = 10\text{V}, I_D = 20\text{A}$  | -    | 100  | -         | S                |
| <b>Dynamic Characteristics<sup>5</sup></b>   |                             |   |      |      |           |                  |
| Input Capacitance  | $C_{\text{iss}}$            | $V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$                  | -    | 5210 | -         | $\text{pF}$      |
| Output Capacitance   | $C_{\text{oss}}$            |   | -    | 430  | -         |                  |
| Reverse Transfer Capacitance   | $C_{\text{rss}}$            |   | -    | 325  | -         |                  |
| Gate Resistance  | $R_G$                       | $f = 1\text{MHz}$   | -    | 1.1  | -         | $\Omega$         |
| <b>Switching Characteristics<sup>5</sup></b>   |                             |   |      |      |           |                  |
| Total Gate Charge  | $Q_g$                       | $V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 20\text{V}, I_D = 20\text{A}$                | -    | 95   | -         | $\text{nC}$      |
| Gate-Source Charge   | $Q_{gs}$                    |   | -    | 9.5  | -         |                  |
| Gate-Drain Charge  | $Q_{gd}$                    |   | -    | 18.5 | -         |                  |
| Turn-On Delay Time   | $t_{\text{d(on)}}$          | $V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 20\text{V}, R_G = 3\Omega, I_D = 20\text{A}$ | -    | 15.8 | -         | $\text{ns}$      |
| Rise Time  | $t_r$                       |   | -    | 30.5 | -         |                  |
| Turn-Off Delay Time  | $t_{\text{d(off)}}$         |   | -    | 150  | -         |                  |
| Fall Time  | $t_f$                       |   | -    | 82   | -         |                  |
| Body Diode Reverse Recovery Time   | $t_{rr}$                    | $I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$                                       | -    | 32   | -         | $\text{ns}$      |
| Body Diode Reverse Recovery Charge   | $Q_{rr}$                    |   | -    | 19.2 | -         | $\text{nC}$      |
| <b>Drain-Source Body Diode Characteristics</b>                                       |                             |   |      |      |           |                  |
| Diode Forward Voltage <sup>4</sup>   | $V_{\text{SD}}$             | $I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$   | -    | -    | 1.2       | V                |
| Continuous Source Current  | $T_C=25^\circ\text{C}$      | $I_S$   | -    | -    | 125       | A                |

## Notes:

- Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
- The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=52\text{A}$ .
- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
- This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

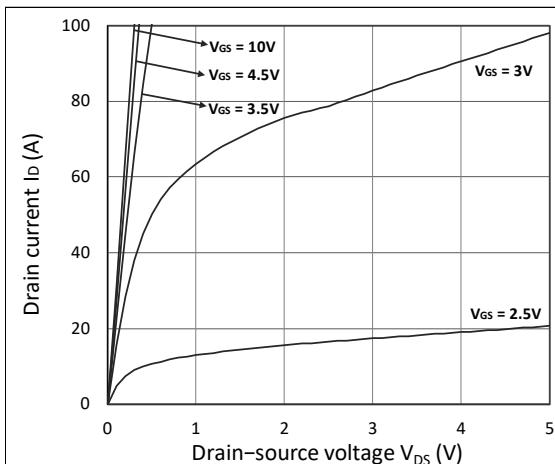


Figure 1. Output Characteristics

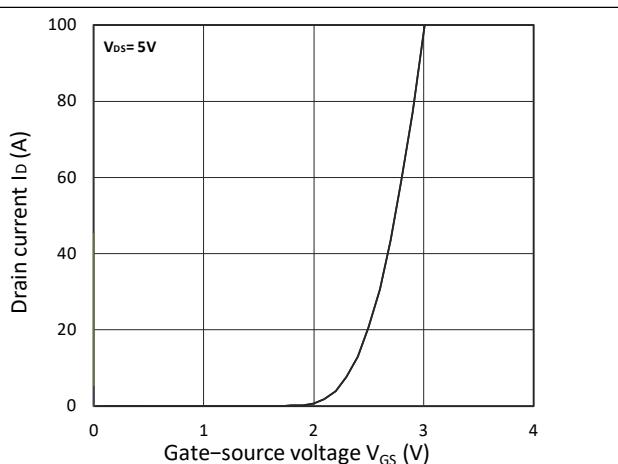


Figure 2. Transfer Characteristics

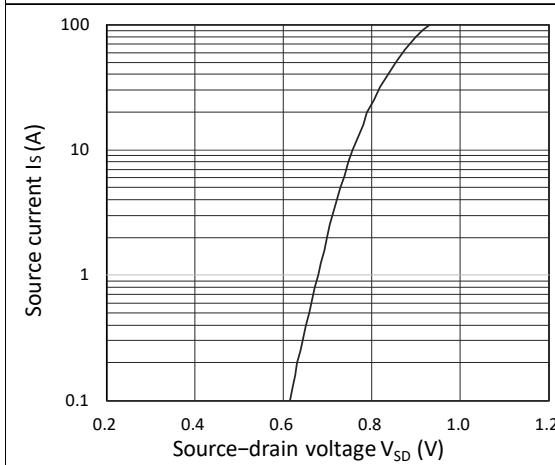
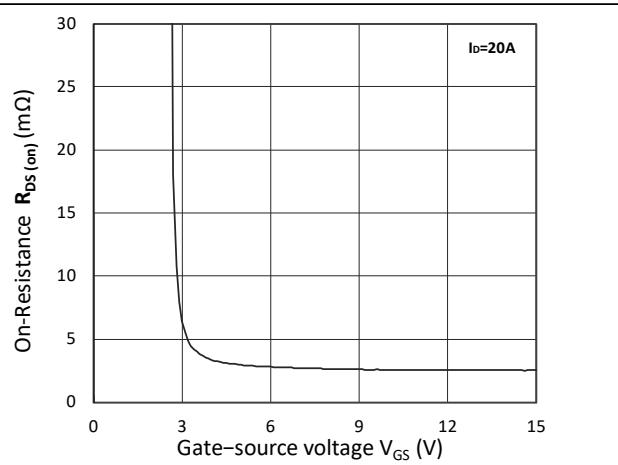
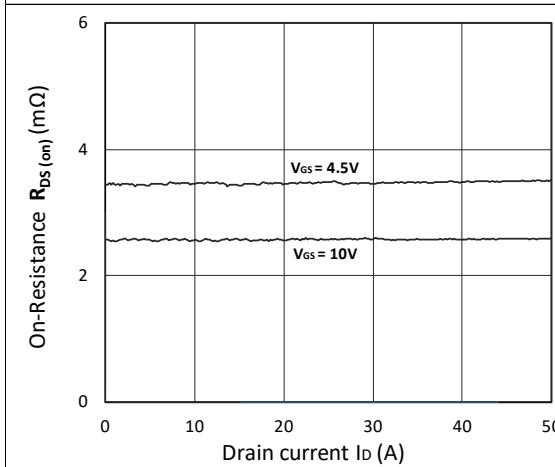
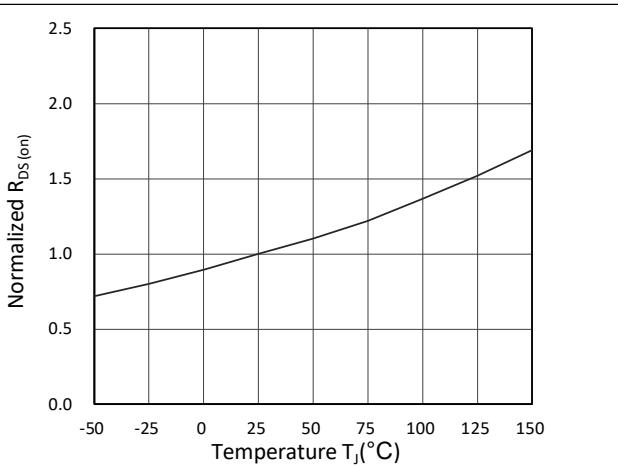
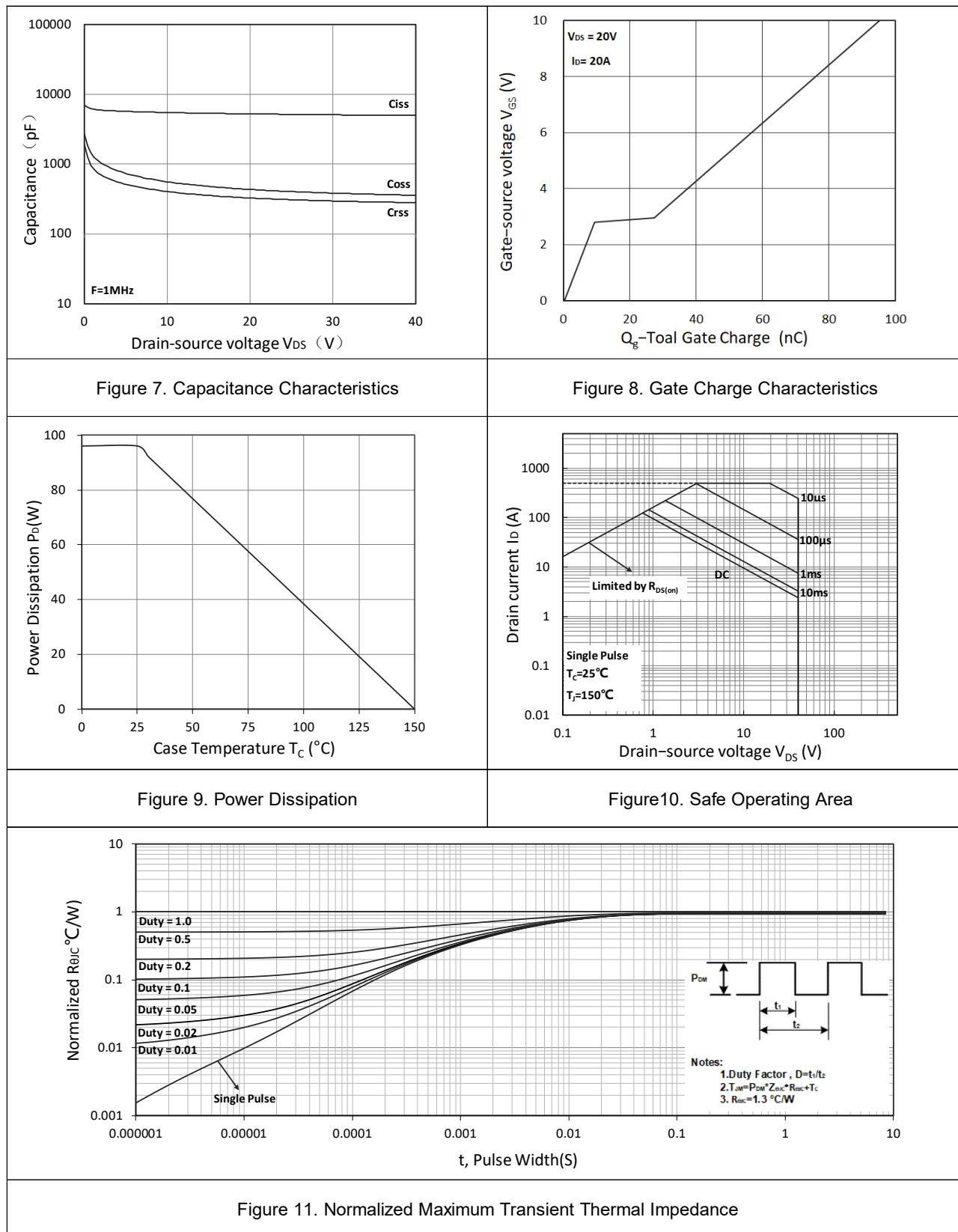


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature



## Test Circuit

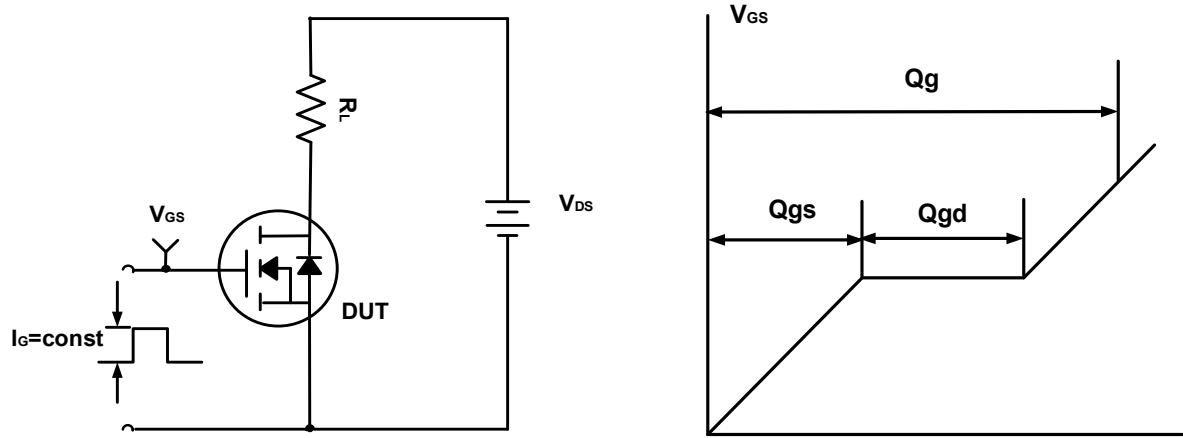


Figure A. Gate Charge Test Circuit &amp; Waveforms

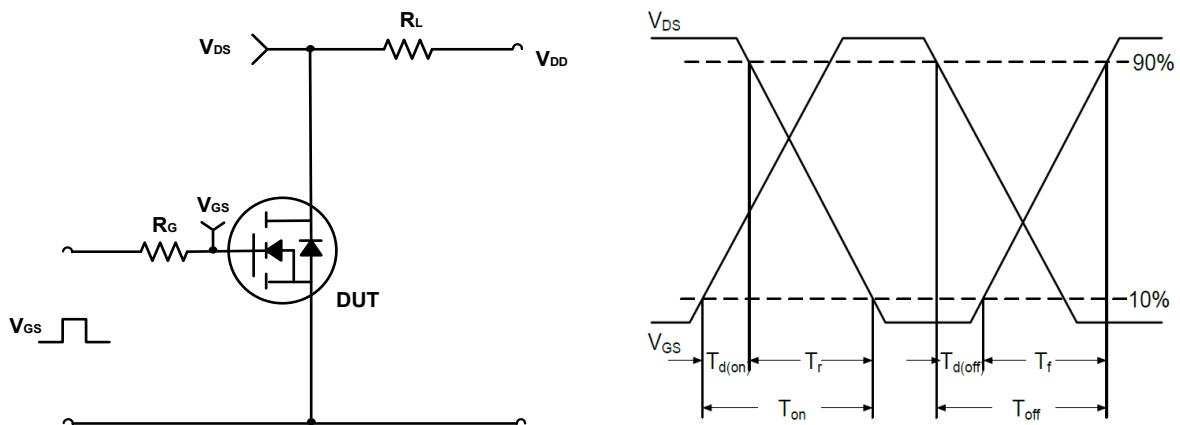


Figure B. Switching Test Circuit &amp; Waveforms

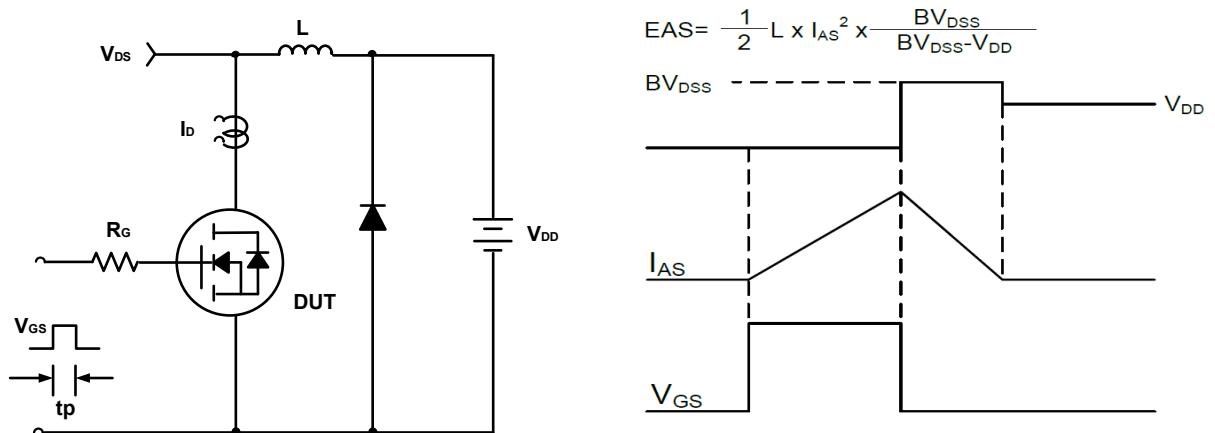
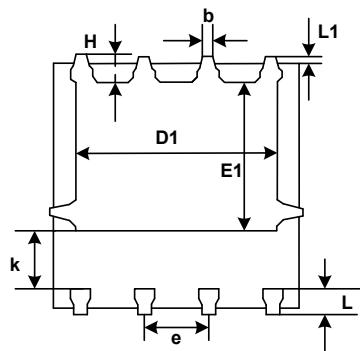
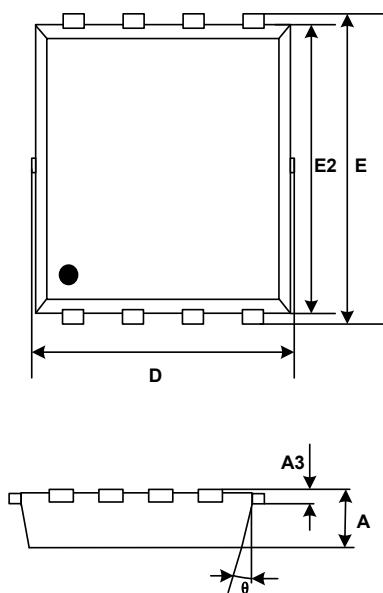


Figure C. Unclamped Inductive Switching Circuit &amp; Waveforms

# WMB100N04TS

## Mechanical Dimensions for PDFN5060-8L

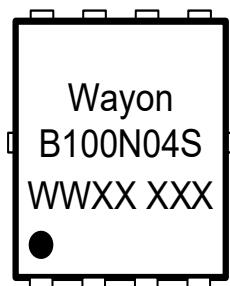
### COMMON DIMENSIONS



| SYMBOL | MM      |      |
|--------|---------|------|
|        | MIN     | MAX  |
| A      | 0.90    | 1.20 |
| A3     | 0.15    | 0.35 |
| D      | 4.80    | 5.40 |
| E      | 5.90    | 6.35 |
| D1     | 3.61    | 4.31 |
| E1     | 3.30    | 3.92 |
| E2     | 5.50    | 6.06 |
| k      | 1.10    | -    |
| b      | 0.30    | 0.51 |
| e      | 1.27BSC |      |
| L      | 0.38    | 0.71 |
| L1     | 0.05    | 0.36 |
| H      | 0.38    | 0.71 |
| θ      | 0°      | 12°  |

**Ordering Information**

| Part        | Package     | Marking  | Packing method |
|-------------|-------------|----------|----------------|
| WMB100N04TS | PDFN5060-8L | B100N04S | Tape and Reel  |

**Marking Information**

B100N04S= Device code

WWXX XXX= Date code